

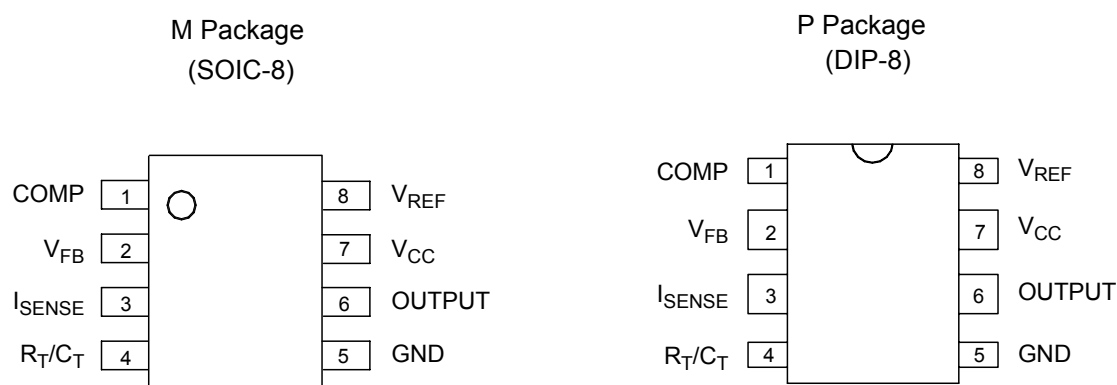
**CURRENT MODE PWM CONTROLLER****AP384XC****Pin Configuration**

Figure 2. Pin Configuration of AP3842C/3C/4C/5C (Top View)

Pin Description

Pin Number	Pin Name	Function
1	COMP	This pin is the Error Amplifier output and is made available for loop compensation.
2	V _{FB}	The inverting input of the Error Amplifier. It is normally connected to the switching power supply output through a resistor divider.
3	I _{SENSE}	A voltage proportional to inductor current is connected to this input. The PWM uses this information to terminate the output switch conduction.
4	R _T /C _T	The Oscillator frequency and maximum output duty cycle are programmed by connecting resistor R _T to V _{REF} and capacitor C _T to ground. Operation to 500 kHz is possible.
5	GND	The combined control circuitry and power ground.
6	OUTPUT	This output directly drives the gate of a power MOSFET. Peak currents up to 1.0 A are sourced and sunk by this pin.
7	V _{CC}	The positive supply of the control IC.
8	V _{REF}	This is the reference output. It provides charging current for capacitor C _T through resistor R _T .

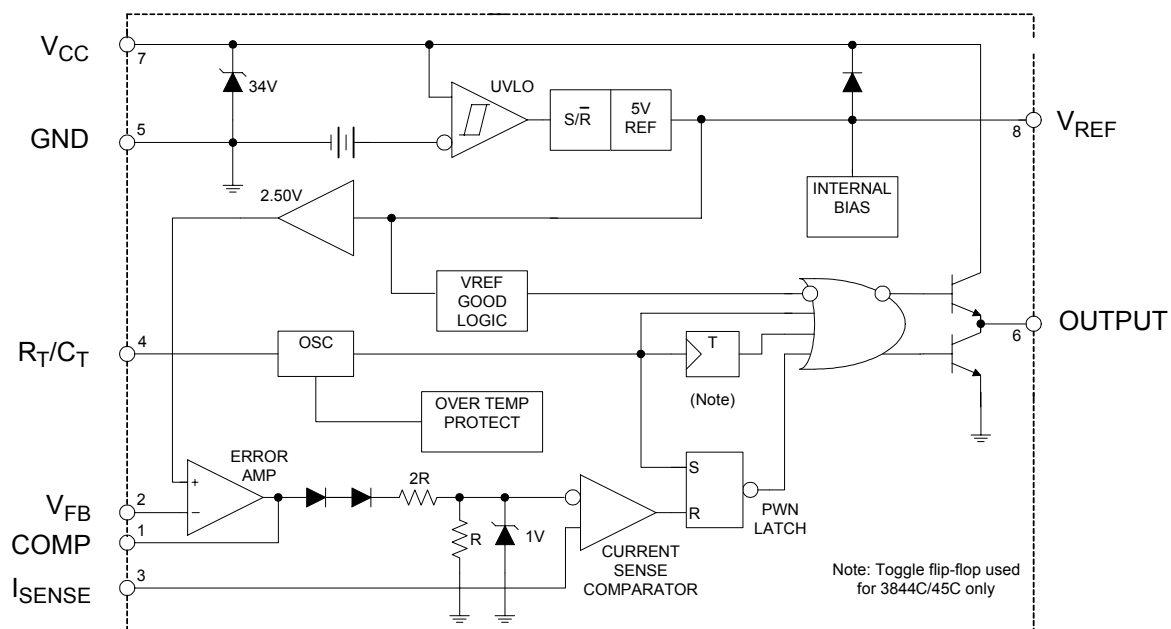
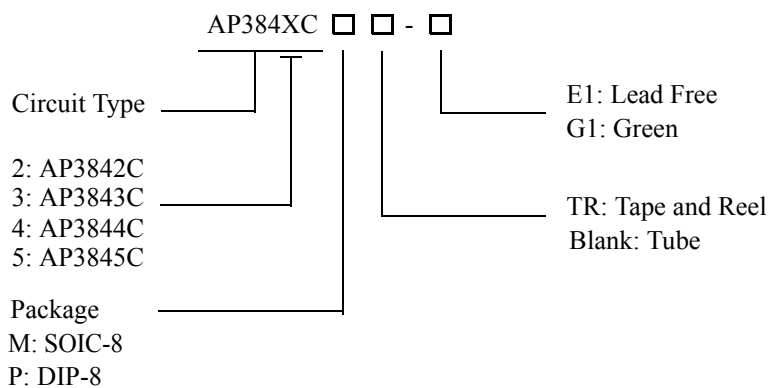
**CURRENT MODE PWM CONTROLLER****AP384XC****Functional Block Diagram**

Figure 3. Functional Block Diagram of AP3842C/3C/4C/5C

**CURRENT MODE PWM CONTROLLER****AP384XC****Ordering Information**

Package	Temperature Range	Part Number		Marking ID		Packing Type
		Lead Free	Green	Lead Free	Green	
SOIC-8	-40 to 85°C	AP3842/3/4/5CM-E1	AP3842/3/4/5CM-G1	3842/3/4/5CM-E1	3842/3/4/5CM-G1	Tube
		AP3842/3/4/5CMTR-E1	AP3842/3/4/5CMTR-G1	3842/3/4/5CM-E1	3842/3/4/5CM-G1	Tape & Reel
DIP-8		AP3842/3/4/5CP-E1	AP3842/3/4/5CP-G1	AP3842/3/4/5CP-E1	AP3842/3/4/5CP-G1	Tube

BCD Semiconductor's Pb-free products, as designated with "E1" suffix in the part number, are RoHS compliant. Products with "G1" suffix are available in green packages.

**CURRENT MODE PWM CONTROLLER****AP384XC****Absolute Maximum Ratings (Note 1, 2)**

Parameter	Symbol	Value		Unit
Supply Voltage	V_{CC}	30		V
Output Current	I_O	± 1		A
Analog Inputs	$V(ANA)$	-0.3 to 6.3		V
Error Amp Output Sink Current	$I_{SINK(E.A)}$	10		mA
Power Dissipation at $T_A < 25\text{ }^{\circ}\text{C}$ (DIP-8)	P_D (Note 3)	1000		mW
Power Dissipation at $T_A < 25\text{ }^{\circ}\text{C}$ (SOIC-8)	P_D (Note 3)	460		mW
Junction Operating Temperature	T_J	-40 to 150		$^{\circ}\text{C}$
Thermal Resistance (Junction to Ambient)	θ_{JA}	DIP-8	140	$^{\circ}\text{C}/\text{W}$
		SOIC-8	160	$^{\circ}\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-65 to 150		$^{\circ}\text{C}$
Lead Temperature (Soldering, 10sec)	T_{LEAD}	+300		$^{\circ}\text{C}$
ESD (Machine Model)		250		V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Note 2: All voltages are with respect to pin 5 and all currents are positive into specified terminal.

Note 3: Board thickness 1.6mm, board dimension 90mm X 90mm.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Oscillation Frequency	f		500	KHz
Ambient Temperature	T_A	-40	85	$^{\circ}\text{C}$

**CURRENT MODE PWM CONTROLLER****AP384XC****Electrical Characteristics**(V_{CC}=15V, R_T=10kΩ C_T=3.3nF, T_A=25°C, unless otherwise specified.)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
REFERENCE SECTION						
Reference Output Voltage	V _{REF}	T _A =25°C, I _{REF} =1mA	4.90	5.00	5.10	V
Total Output Variation		Line, Load, Temp.	4.82		5.18	V
Line Regulation	ΔV _{REF}	12V ≤ V _{CC} ≤ 25V		4	15	mV
Load Regulation	ΔV _{REF}	1mA ≤ I _{REF} ≤ 20mA		4	15	mV
Short Circuit Output Current	I _{SC}	T _A =25°C		-100	-180	mA
Temperature Stability		(Note 6)		0.3		mV/°C
OSCILLATOR SECTION						
Oscillation Frequency	f	T _A =25°C	47	52	57	KHz
Oscillator Amplitude	V _{OSC}	Pin 4, peak to peak (Note 6)		1.7		V
Temperature Stability		(Note 6)		2.5		%
Voltage Stability		12V ≤ V _{CC} ≤ 25V		0.2	1	%
Discharge Current		V _{pin 4} = 2V (Note 7)	8.5	9.5	10.5	mA
ERROR AMPLIFIER SECTION						
Input Voltage	V _I	V _{pin 1} = 2.5V	2.45	2.50	2.55	V
Output Sink Current	I _{SINK}	V _{pin 1} = 1.1V	5	8		mA
Output Source Current	I _{SOURCE}	V _{pin 1} = 5V	-0.5	-0.8		mA
High Output Voltage	V _{OH}	R _L = 15kΩ to GND	5	7		V
Low Output Voltage	V _{OL}	R _L = 15kΩ to pin 8		0.7	1.1	V
Voltage Gain		2V ≤ V _O ≤ 4V	65	90		dB
Power Supply Rejection Ratio	PSRR	12V ≤ V _{CC} ≤ 25V	60	70		dB
CURRENT SENSE SECTION						
Maximum Input Signal	V _I (MAX)	V _{pin 1} = 5V (Note 4)	0.9	1	1.1	V
Gain	GV	(Note 4, 5)	2.85	3	3.15	V/V
Power Supply Rejection Ratio	PSRR	12V ≤ V _{CC} ≤ 25V (Note 4, 6)		70		dB
Delay to Output		V _{pin 3} = 0 to 2V (Note 6)		150	300	ns
Input Bias Current	I _{BIAS}			-3	-10	μA
OUTPUT SECTION						
Low Output Voltage	V _{OL}	I _{SINK} = 20mA		0.1	0.4	V
		I _{SINK} = 200mA		1.4	2.2	V
High Output Voltage	V _{OH}	I _{SOURCE} = 20mA	13	14		V
		I _{SOURCE} = 200mA	12	13		V
Rise Time	t _R	T _A =25°C, C _L =1nF (Note 6)		50	150	ns
Fall Time	t _F	T _A =25°C, C _L =1nF (Note 6)		50	150	ns

**CURRENT MODE PWM CONTROLLER****AP384XC****Electrical Characteristics (Continued)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
UNDER -VOLTAGE LOCKOUT SECTION						
Start Threshold	V _{TH} (ST)	AP3842C/AP3844C	15	16	17	V
		AP3843C/AP3845C	7.8	8.4	9.0	V
Min. Operation Voltage (After Turn On)	V _{OPR} (Min.)	AP3842C/AP3844C	8.5	10.0	11.5	V
		AP3843C/AP3845C	7.0	7.6	8.2	V
PWM SECTION						
Max. Duty Cycle	D(Max.)	AP3842C/AP3843C	95	97	100	%
	D(Max.)	AP3844C/AP3845C	46	48	50	%
Min. Duty Cycle	D(Min.)				0	%
TOTAL STANDBY CURRENT SECTION						
Start-up Current	I _{ST}	AP3842C/AP3844C, V _{CC} =14V		50	80	μA
		AP3843C/AP3845C, V _{CC} =6.5V		50	80	
Operating Supply Current	I _{CC} (OPR)	V _{pin3} =V _{pin2} =0V		8	12	mA
Zener Voltage	V _Z	I _{CC} =25mA	30	34		V
OVER-TEMPERATURE PROTECT SECTION						
Shutdown Temperature	T _{SHUT}	(Note 6)		155		°C
Temperature Hysteresis	T _{HYS}	(Note 6)		25		°C

Note 4: Parameters are tested at trip point of latch with $V_{pin2} = 0$.

Note 5: Here gain is defined as:

$$A = \frac{\Delta V_{Pin 1}}{\Delta V_{Pin 3}}, 0 \leq V_{pin3} \leq 0.8V$$

Note 6: These parameters, although guaranteed, are not 100% tested in production.

Note 7: This parameter is measured with $R_T=10k\Omega$ to V_{REF} , it contributes 0.3mA of current to the measured value.

So the total current flowing into the CT pin will be 0.3mA higher than the measured value approximately.

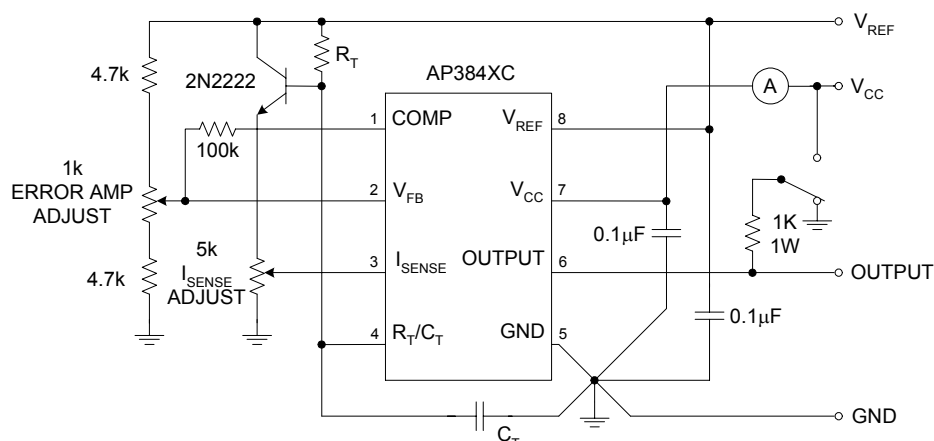


Figure 4. Basic Test Circuit

**CURRENT MODE PWM CONTROLLER****AP384XC****Electrical Characteristics (Continued)**

Figure 4 is the basic test circuit for AP384XC. In testing, the high peak currents associated with capacitive loads necessitate careful grounding techniques. Timing and bypass capacitors should be connected close to pin 5 in a single point ground. The transistor and 5k potentiometer are used to sample the oscillator waveform and apply an adjustable ramp to pin 3.

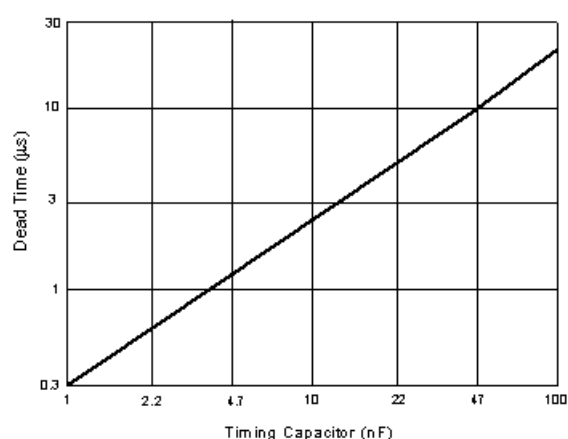
Typical Performance Characteristics

Figure 5. Oscillator Dead Time vs. Timing Capacitor

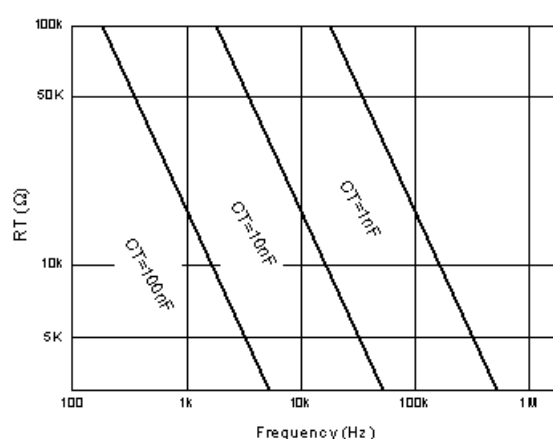


Figure 6. Timing Resistor vs. Frequency

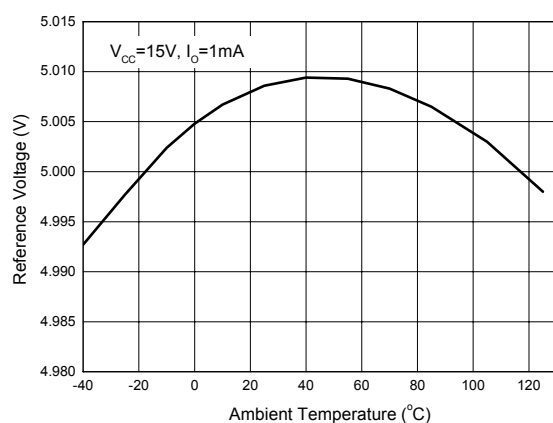


Figure 7. Reference Voltage vs. Ambient Temperature

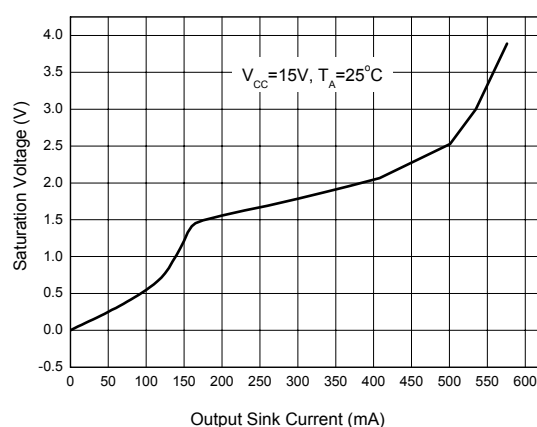


Figure 8. Output Saturation Characteristics

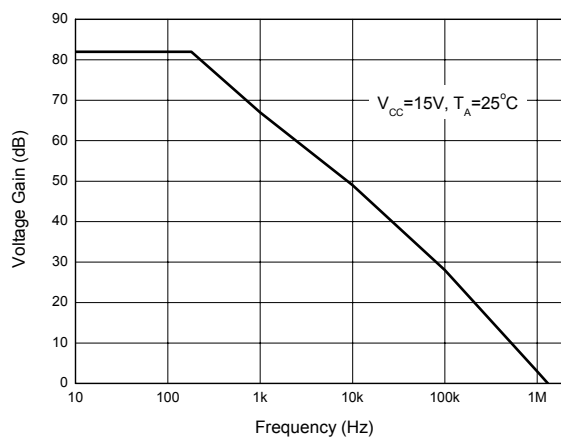
**CURRENT MODE PWM CONTROLLER****AP384XC****Typical Performance Characteristics (Continued)**

Figure 9. Error Amplifier Open-Loop Frequency Response

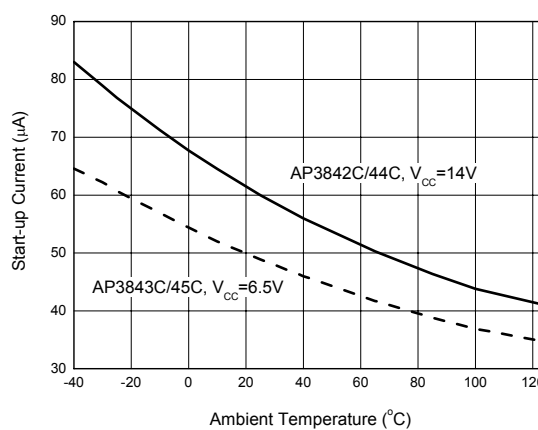


Figure 10. Start-up Current vs. Ambient Temperature

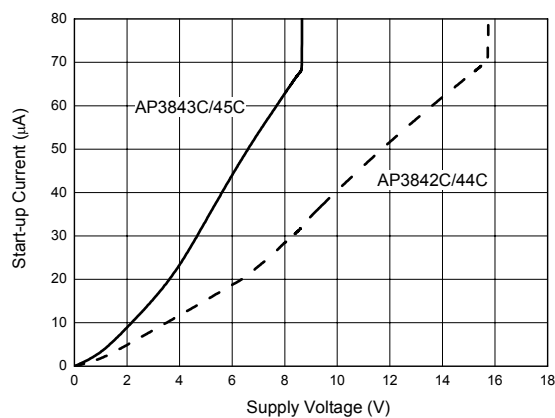


Figure 11. Start-up Current vs. Supply Voltage

CURRENT MODE PWM CONTROLLER

AP384XC

Typical Application

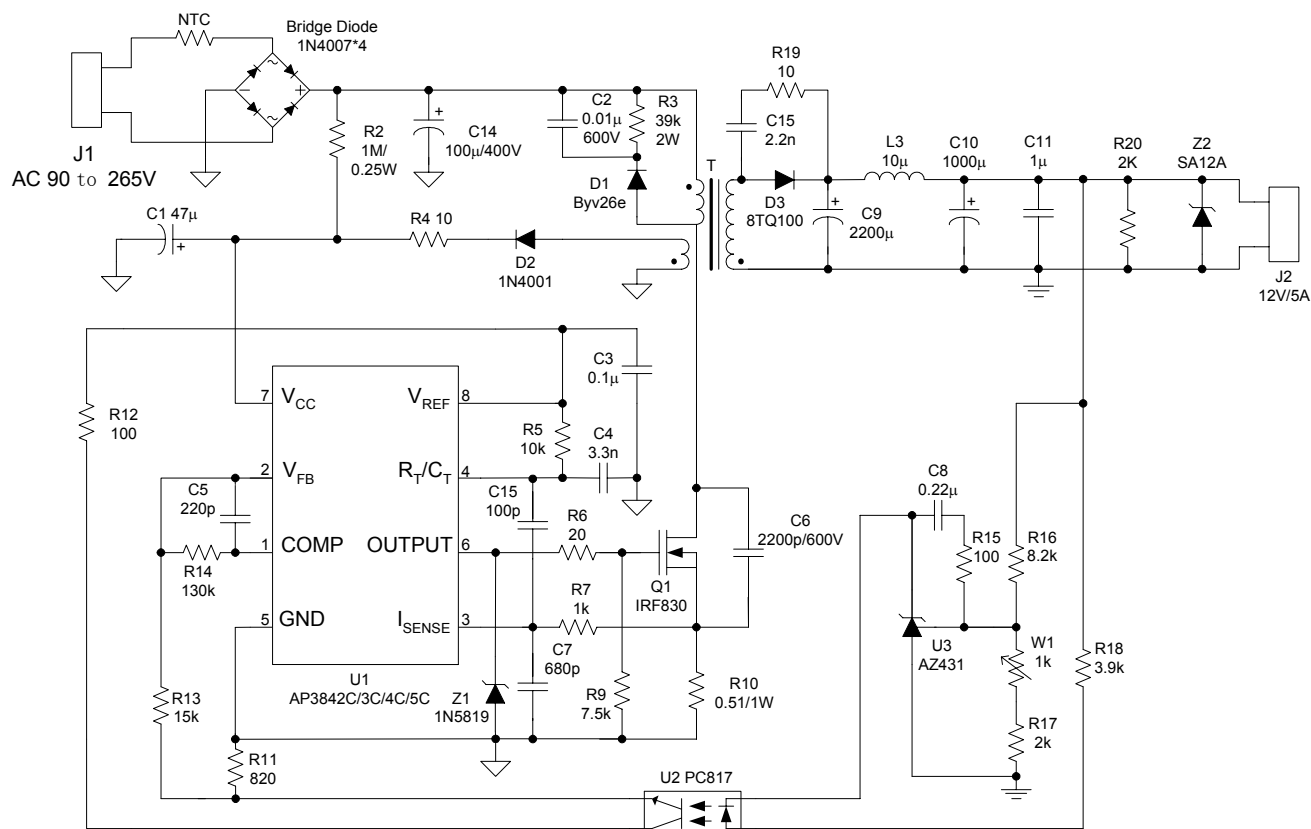
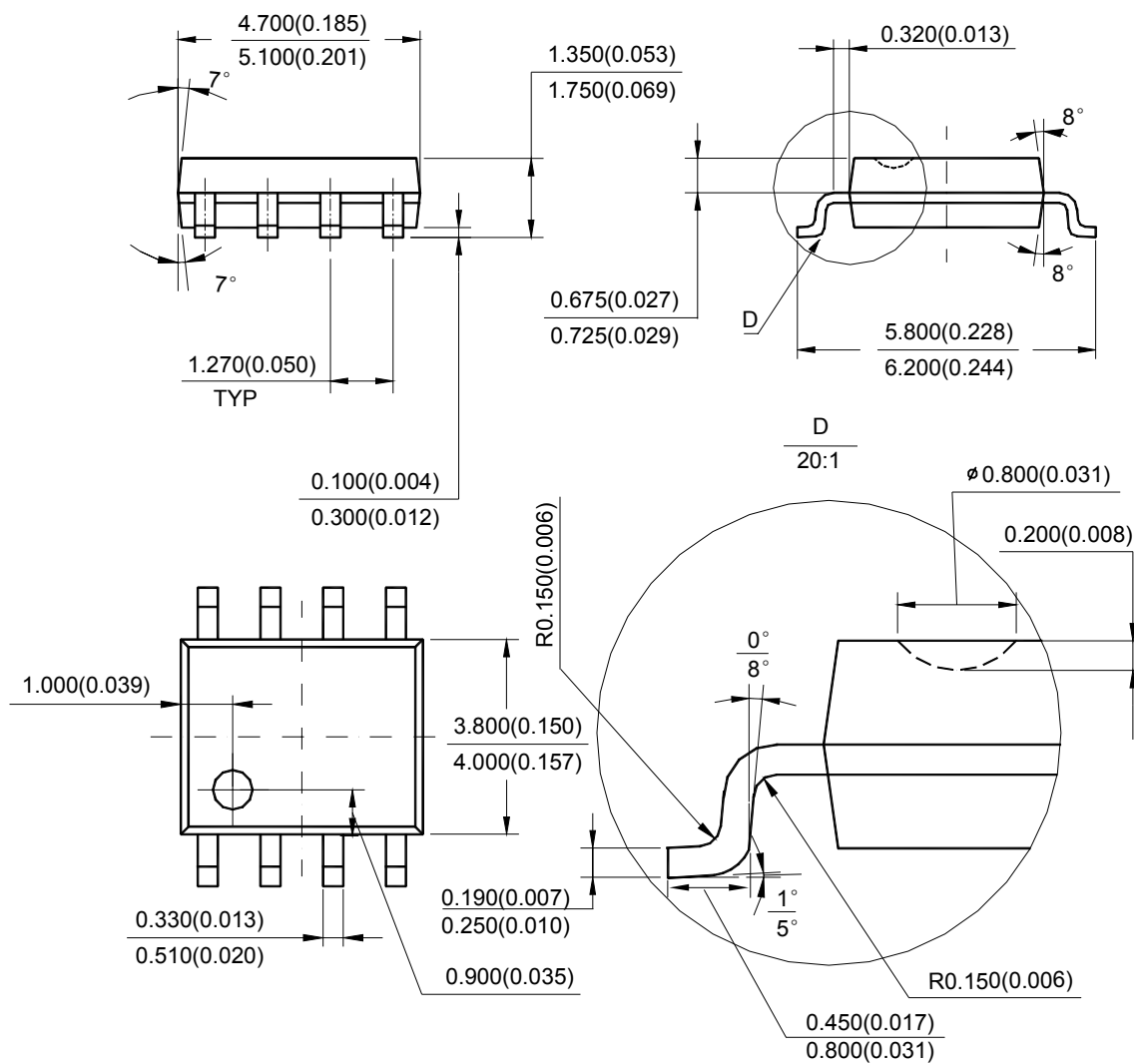
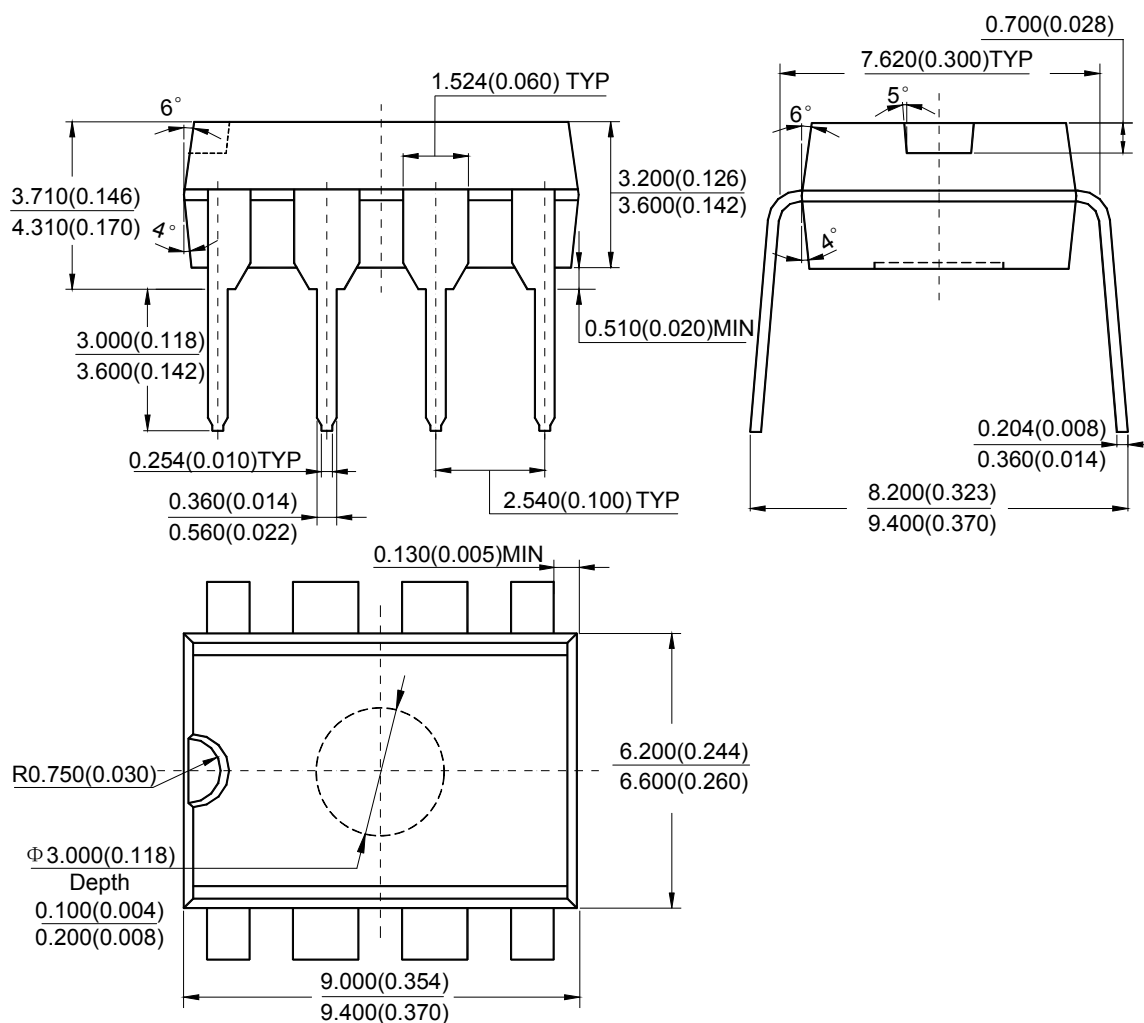


Figure 12. Typical Application of AP3842C/3C/4C/5C

**CURRENT MODE PWM CONTROLLER****AP384XC****Mechanical Dimensions****SOIC-8****Unit: mm(inch)**

Note: Eject hole, oriented hole and mold mark is optional.

**CURRENT MODE PWM CONTROLLER****AP384XC****Mechanical Dimensions (Continued)****DIP-8****Unit: mm(inch)**

Note: Eject hole, oriented hole and mold mark is optional.



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